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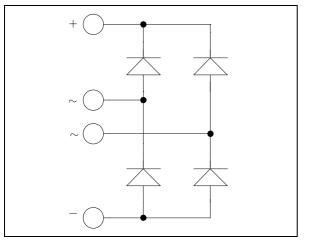
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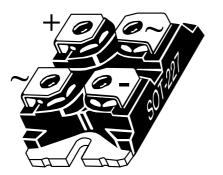


APT40DS04HJ

ISOTOP[®] Schottky Diode Full Bridge Power Module

$V_{RRM} = 45V$ $I_F = 40A$ (*a*) $Tc = 80^{\circ}C$





Application

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High current
- Very low stray inductance
- High level of integration
- ISOTOP[®] Package (SOT-227)

Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit
V _R	Maximum DC reverse Voltage			45	V
V _{RRM}	Maximum Peak Repetitive Reverse Voltage			43	
I _{FAV}	ectangular, $d = 0.5$		$T_C = 80^{\circ}C$	40	٨
I _{FSM}	Non-Repetitive Forward Surge Current	t = 10ms	$T_J = 45^{\circ}C$	450	А

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



All ratings (a) $T_j = 25^{\circ}C$ unless otherwise specified

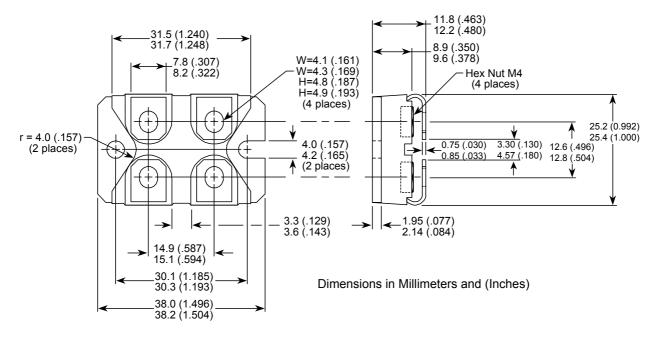
Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Тур	Max	Unit
I _R	Reverse Current	$V_R = 45V$	$T_j = 25^{\circ}C$		20		mA
			$T_{j} = 125^{\circ}C$		200		
$V_{\rm F}$	Forward Voltage	$I_F = 40A$	$T_j = 25^{\circ}C$		0.58		v
			$T_{j} = 125^{\circ}C$		0.48		

Thermal and package characteristics

Symbol	Characteristic	Min	Тур	Max	Unit
R _{thJC}	Junction to Case Thermal resistance			1.1	°C/W
R _{thJA}	Junction to Ambient			20	C/ W
VISOL	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz	2500			V
T_J, T_{STG}	Storage Temperature Range	-55		150	°C
T _L	Max Lead Temp for Soldering:0.063" from case for 10 sec			300	C
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

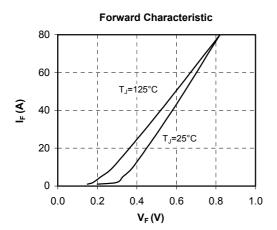
SOT-227 (ISOTOP®) Package Outline

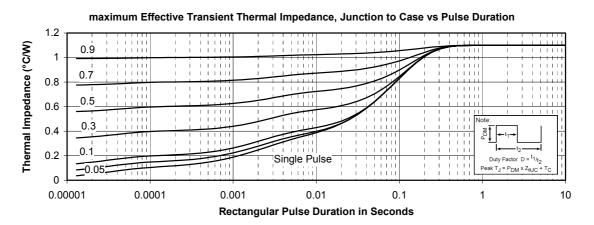


APT40DS04HJ - Rev 1 October, 2012



Typical Performance Curve





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APT40DS04HJ

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Life Support Application

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